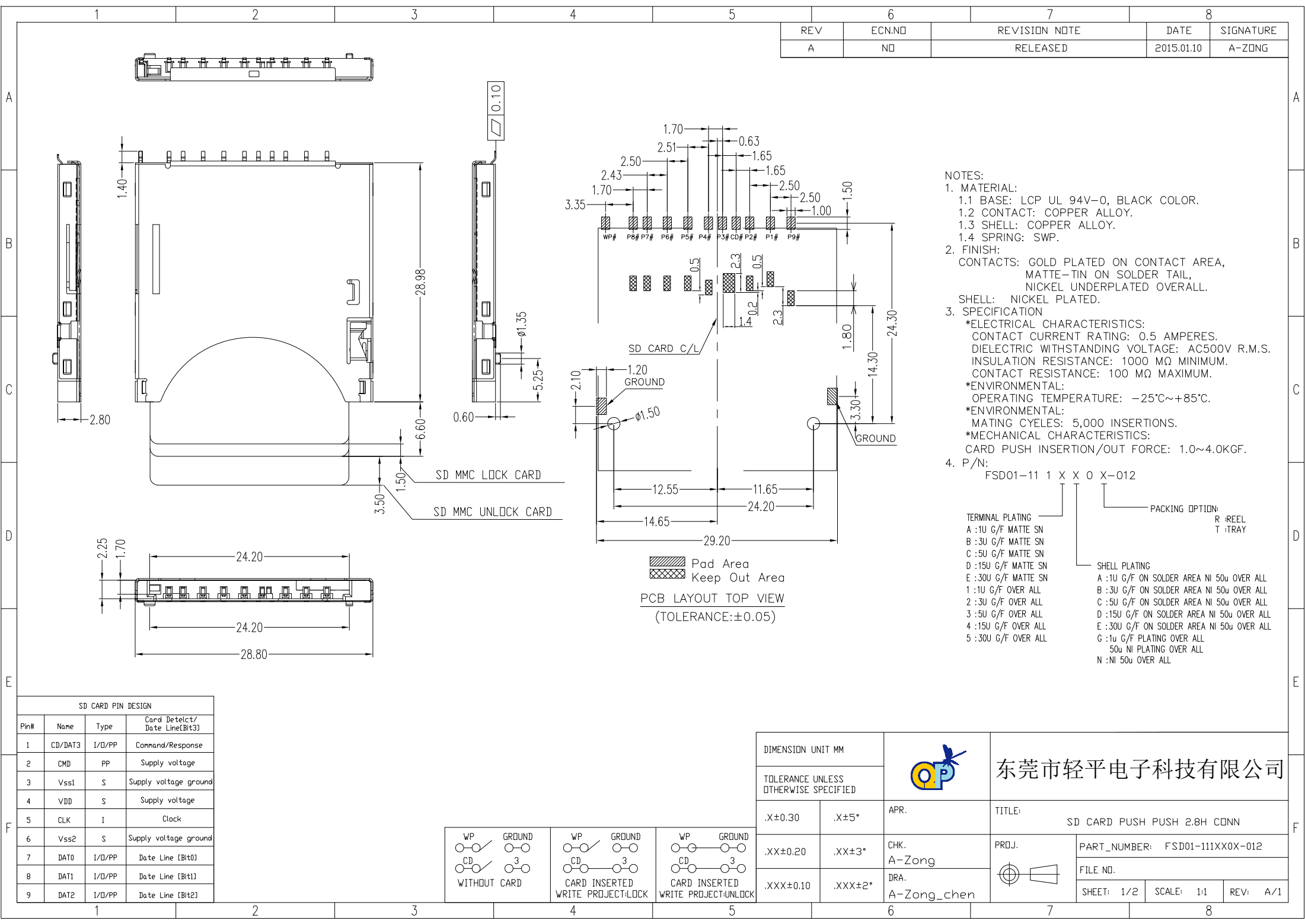


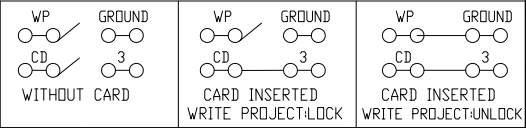


REV		ECN.NO	REVISION NOTE	DATE	SIGNATURE
A		NO	RELEASED	2015.01.10	A-ZONG

- NOTES:
- MATERIAL:
 - 1.1 BASE: LCP UL 94V-0, BLACK COLOR.
 - 1.2 CONTACT: COPPER ALLOY.
 - 1.3 SHELL: COPPER ALLOY.
 - 1.4 SPRING: SWP.
 - FINISH:
 - CONTACTS: GOLD PLATED ON CONTACT AREA, MATTE-TIN ON SOLDER TAIL, NICKEL UNDERPLATED OVERALL.
 - SHELL: NICKEL PLATED.
 - SPECIFICATION
 - *ELECTRICAL CHARACTERISTICS:
 - CONTACT CURRENT RATING: 0.5 AMPERES.
 - DIELECTRIC WITHSTANDING VOLTAGE: AC500V R.M.S.
 - INSULATION RESISTANCE: 1000 MΩ MINIMUM.
 - CONTACT RESISTANCE: 100 MΩ MAXIMUM.
 - *ENVIRONMENTAL:
 - OPERATING TEMPERATURE: -25°C~+85°C.
 - *ENVIRONMENTAL:
 - MATING CYCLES: 5,000 INSERTIONS.
 - *MECHANICAL CHARACTERISTICS:
 - CARD PUSH INSERTION/OUT FORCE: 1.0~4.0KGF.
 - P/N:
 - FSD01-11 1 X X 0 X-012

TERMINAL PLATING		PACKING OPTION:	
A :1U G/F MATTE SN		R :REEL	
B :3U G/F MATTE SN		T :TRAY	
C :5U G/F MATTE SN			
D :15U G/F MATTE SN			
E :30U G/F MATTE SN			
1 :1U G/F OVER ALL			
2 :3U G/F OVER ALL			
3 :5U G/F OVER ALL			
4 :15U G/F OVER ALL			
5 :30U G/F OVER ALL			
		SHELL PLATING	
		A :1U G/F ON SOLDER AREA NI 50u OVER ALL	
		B :3U G/F ON SOLDER AREA NI 50u OVER ALL	
		C :5U G/F ON SOLDER AREA NI 50u OVER ALL	
		D :15U G/F ON SOLDER AREA NI 50u OVER ALL	
		E :30U G/F ON SOLDER AREA NI 50u OVER ALL	
		G :1u G/F PLATING OVER ALL	
		50u NI PLATING OVER ALL	
		N :NI 50u OVER ALL	

SD CARD PIN DESIGN			
Pin#	Name	Type	Card Detect/Date Line[Bit3]
1	CD/DAT3	I/O/PP	Command/Response
2	CMD	PP	Supply voltage
3	Vss1	S	Supply voltage ground
4	VDD	S	Supply voltage
5	CLK	I	Clock
6	Vss2	S	Supply voltage ground
7	DAT0	I/O/PP	Date Line [Bit0]
8	DAT1	I/O/PP	Date Line [Bit1]
9	DAT2	I/O/PP	Date Line [Bit2]



DIMENSION UNIT MM			
TOLERANCE UNLESS OTHERWISE SPECIFIED			
.X±0.30	.X±5°	APR.	TITLE: SD CARD PUSH PUSH 2.8H CONN
.XX±0.20	.XX±3°	CHK. A-Zong	PROJ. PART_NUMBER: FSD01-111XX0X-012
.XXX±0.10	.XXX±2°	DRA. A-Zong_chen	FILE NO.
		SHEET: 1/2 SCALE: 1:1 REV: A/1	